

**Abstract of the Disclosure**

A semiconductor integrated circuit includes a first pad mounted on a main surface of a semiconductor substrate, a second pad mounted on the main surface and positioned adjacent to the first pad, a pad joint mounted between the first pad and the second pad to connect the first pad and the second pad, a first signal input/output circuit including a first output buffer connected to the first pad, a second signal input/output circuit including a second input buffer connected to the second pad, and a second output buffer connected to the second pad and including an output section having a controllable output impedance, an input/output signal control circuit connected to the first signal input/output circuit and the second signal input/output circuit. The input/output signal control circuit includes a first latch circuit connected to an input section of the first output buffer, a second latch circuit connected to an output section of the second input buffer, and a control switch connected to an input section of the first output buffer and an input section of the second output buffer.